

1.2V Drive Nch MOSFET

RUU002N05

• Structure

Silicon N-channel MOSFET

Features

1) High speed switing.

- 2) Small package(UMT3).
- 3)Ultra low voltage drive(1.2V drive).

Application

Switching

• Packaging specifications

_				
	Package	Taping		
Туре	Code	T106		
	Basic ordering unit (pieces)	3000		
RUU002N0	0			

• Absolute maximum ratings (Ta = 25°C)

• Packag	ing specifica	ations						
	Package		Taping					
Туре	Code		T106					
	Basic order	ing unit (pieces)	3000					
RUU002N	05		0					
● Absolu	te maximum	r atings (Ta = 25	(3°		0			
	Paramet	ter	Symbol	Limits	Unit			
Drain-sou	rce voltage		V _{DSS}	50	V			
Gate-sour	ce voltage		V _{GSS}	±8	V			
Drain current		Continuous	I _D	±200	mA			
		Pulsed	I _{DP} *1	±800	mA			
Source current (Body Diode)		Continuous	IS	150	mA			
		Pulsed	1 _{SP} *1	800	mA			
Power dis	sipation		P _D *2	200	mW			
Channel temperature			Tch	150	°C			
Range of storage temperature			Tstg	-55 to +150	°C			

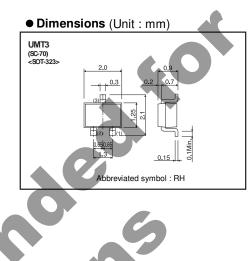
*1 Pw≤10µs, Duty cycle≤1%

*2 Each terminal mounted on a recommended land.

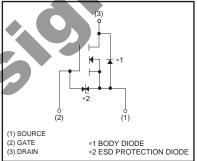
Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	Rth (ch-a)*	625	°C / W

* Each terminal mounted on a recommended land.



Inner circuit



•Electrical characteristics (Ta = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	I _{GSS}	-	-	±10	μA	$V_{GS}=\pm 8V, V_{DS}=0V$
Drain-source breakdown voltage	$V_{(BR)DSS}$	50	-	-	V	I _D =1mA, V _{GS} =0V
Zero gate voltage drain current	I _{DSS}	-	-	1	μA	V_{DS} =50V, V_{GS} =0V
Gate threshold voltage	V _{GS (th)}	0.3	-	1.0	V	V_{DS} =10V, I_{D} =1mA
		-	1.6	2.2		I_{D} =200mA, V_{GS} =4.5V
		-	1.7	2.4		I _D =200mA, V _{GS} =2.5V
Static drain-source on-state resistance	R _{DS (on)} *	-	1.9	2.7	Ω	I _D =100mA, V _{GS} =1.8V
obiotanoo		-	2.0	4.0		I _D =40mA, V _{GS} =1.5V
		-	2.4	7.2		I _D =20mA, V _{GS} =1.2V
Forward transfer admittance	ا Y _{fs} ا*	0.4	-	-	S	I _D =200mA, V _{DS} =10V
nput capacitance	C _{iss}	-	25	-	pF	V _{DS} =10V
Dutput capacitance	C _{oss}	-	6	-	pF	V _{GS} =0V
Reverse transfer capacitance	C _{rss}	-	3	-	рF	f=1MHz
Turn-on delay time	t _{d(on)} *	-	4	-	ns	I _D =100mA, V _{DD} ≒ 30V
Rise time	t _r *	-	6	-	ns	V _{GS} =4.5V
Turn-off delay time	t _{d(off)} *	-	15	-	ns	R _L =300Ω
Fall time	t _f *	-	55	-	ns	B _G =10Ω

*Pulsed

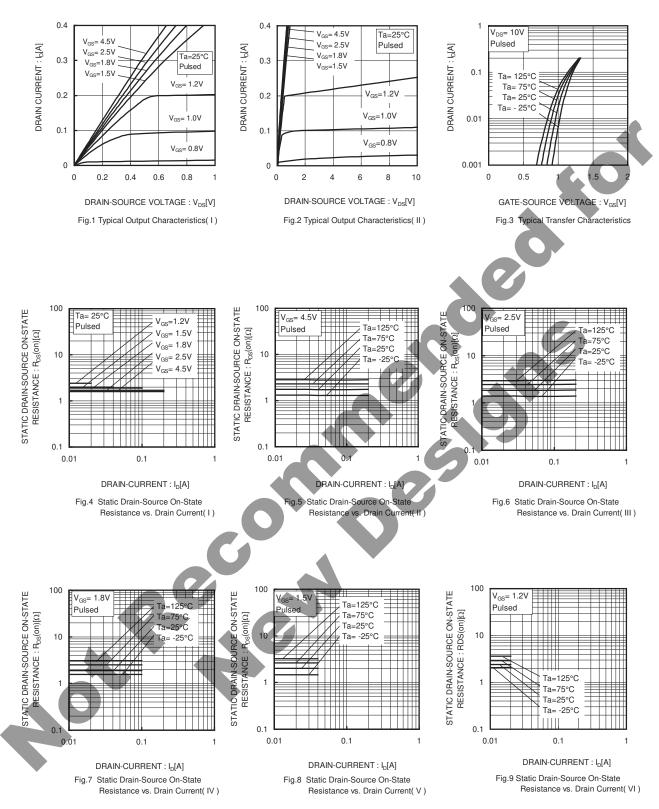
•Body diode characteristics (Source-Drain) (Ta = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	V_{SD}^{*}	-	-	1.2	VC	_s =200mA, V _{GS} =0V
*Pulsed		0		5	2	

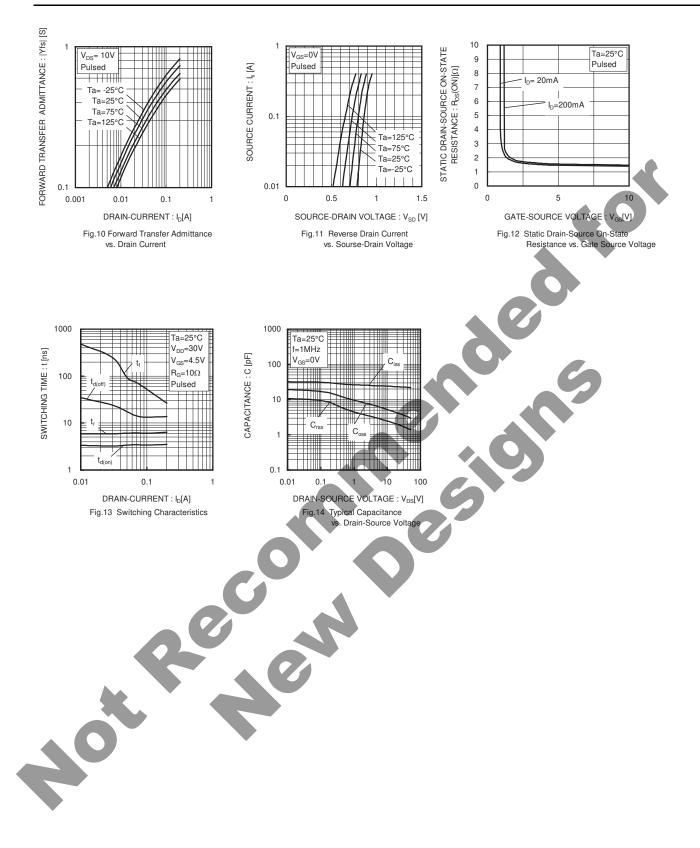
20%

Data Sheet

•Electrical characteristic curves



RUU002N05



Measurement circuits

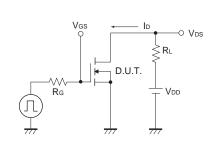
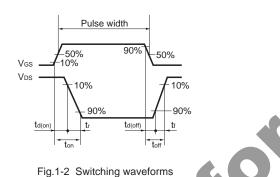
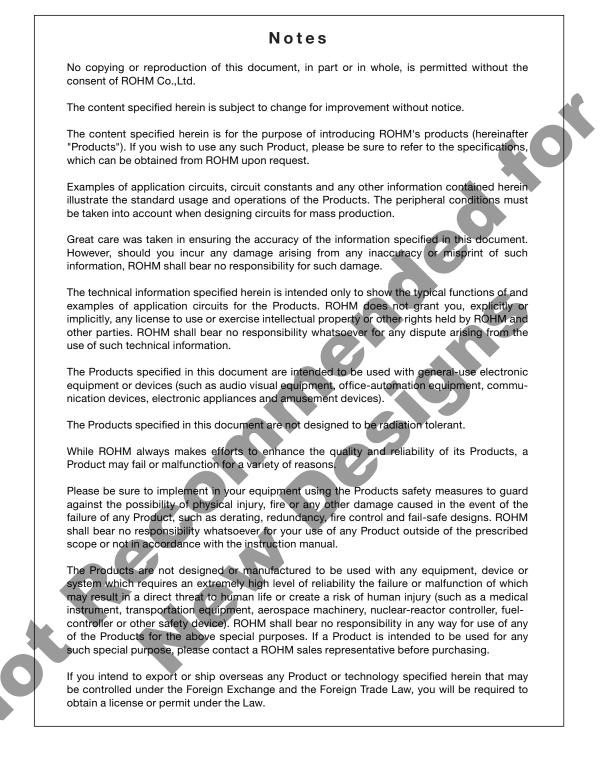


Fig.1-1 Switching time measurement circuit



Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.





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